Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**105 mils**

**125 mils**

**ANODE**

**Top Material: Al**

**Backside Material: CrNiAg**

**Bond Pad Size: .098” X .118”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .105” X .125” DATE: 4/20/16**

**MFG: INT’L RECTIFIER THICKNESS .015” P/N: SC105S045A5P**

**DG 10.1.2**

#### Rev B, 7/19/02